CALL FOR PAPERS

http://www.ieee-socc.org

23rd IEEE International SoC Conference (SOCC)

September 27-29, 2010

Bally's Las Vegas – Nevada – USA

Multibillion transistor System on Chip (SoC) devices, comprised of RF, analog, optical, digital and Micro-Electro-Mechanical Systems (MEMS), are integral parts of ubiquitous communication, entertainment, medical, logistics and carrier products. SoC has been the enabling technology and main thrust behind the evolution of the Internet into a global communication and economic paradigm. Recent advances in systems, deep-submicron and nano process technology are unleashing new opportunities, and also new challenges. These challenges include managing design and verification complexity, EDA tools, on-chip communication, design reuse, handling inevitable faults and the efficient integration of emerging MEMS and nano components into next generation SoCs.

The SOC Conference provides a premier forum for sharing advances in SoC technologies and applications in the areas of digital systems, circuit architectures, design methods, tools and automation, manufacturing and test, and emerging MEMS and nano technologies.

The 23rd SOCC will be held in Las Vegas, Nevada, and will offer three days of technical papers, technical workshops, and a vendor exhibition. Please check our website regularly for updates.

SUBMISSION OF PAPER AND WORKSHOP/TUTORIAL PROPOSALS

Electronic paper submissions require a full paper in *pdf* format, limited to four double-column IEEE format pages, and including figures and references. SOCC 2009 also welcomes embedded tutorial proposals in the related areas of SoC. A proposal with title, a half-page summary, and speaker's short bio should be submitted to the Tutorial Chair by **April 19, 2010**. For corporate sponsorship and exhibition, please refer to the sponsorship package on the website.

The SOCC proceedings will be published by the **IEEE *Xplore*®.**

SOCC TECHNICAL SCOPE

Papers are invited which address new and previously unpublished results in the area of Systems on Chip, and related topics.

- Analog, Mixed-Signal and RF Circuits and Systems
- Digital Signal Processing (DSP) Circuits and Systems (*Video, Multimedia, Control etc.)*
- Embedded Systems, Multi/Many Core Systems and Embedded Memory Technologies
- Wireline & Wireless Communication Circuits and Systems
- System Level Design Methodology, EDA and Design Tools for SoC
- Reconfigurable and Programmable Circuits and Systems, System on Programmable Devices (*FPGAs*)
- Low-Power Circuits, Systems and Design Methodologies
- Signal Integrity, Design for Testability and Design Verification
- Design for Manufacturability, Variation-aware Methodologies
- Network on Chip (NoC) & Interconnects

IMPORTANT DATES

Paper submission deadline:	April 19, 2010	Notification of acceptance:	June 11, 2010
Final camera-ready paper due:	June 25, 2010		

ORGANIZING COMMITTEE

Conference General Chair:	*Thomas Buechner, IBM*	Technical Program Co-Chair:	*Norbert Schuhmann, FHG IIS*
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Please visit the conference web site or contact the SoC Conference office at info@ieee-socc.org for current conference information